

# 74HC11; 74HCT11

## Triple 3-input AND gate

Rev. 6 — 19 November 2015

Product data sheet

## 1. General description

The 74HC11; 74HCT11 is a triple 3-input AND gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## 2. Features and benefits

- Complies with JEDEC standard no. 7A
- Input levels:
  - ◆ For 74HC11: CMOS level
  - ◆ For 74HCT11: TTL level
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

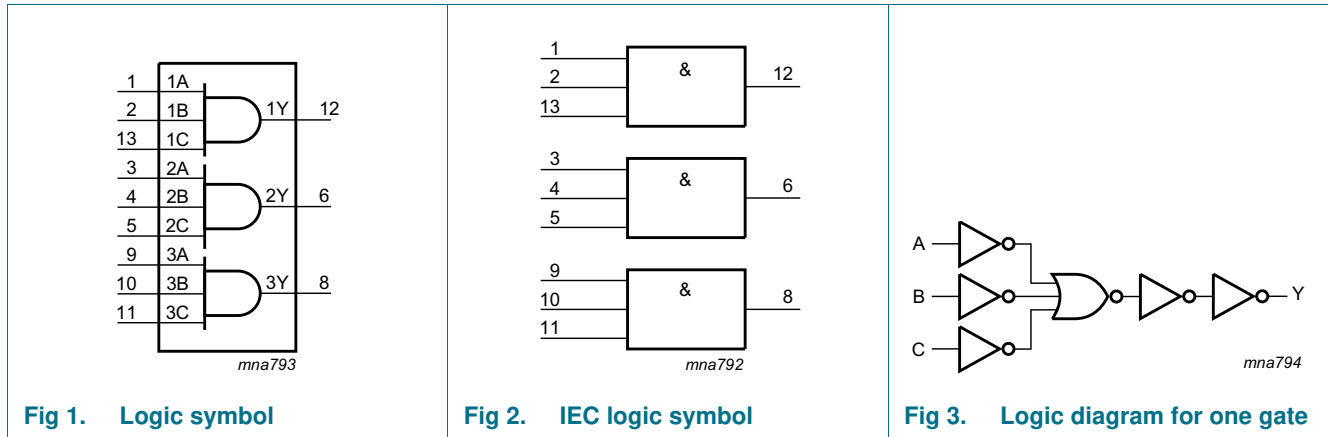
## 3. Ordering information

Table 1. Ordering information

| Type number | Package   |         |  |          |
|-------------|---|---------|--|----------|
|             | Temperature range   | Name    | Description  | Version  |
| 74HC11D     | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SO14    | plastic small outline package; 14 leads; body width 3.9 mm             | SOT108-1 |
| 74HCT11D    |   |         |  |          |
| 74HC11DB    | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SSOP14  | plastic shrink small outline package; 14 leads; body width 5.3 mm      | SOT337-1 |
| 74HCT11DB   |   |         |  |          |
| 74HC11PW    | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP14 | plastic thin shrink small outline package; 14 leads; body width 4.4 mm | SOT402-1 |
| 74HCT11PW   |   |         |  |          |

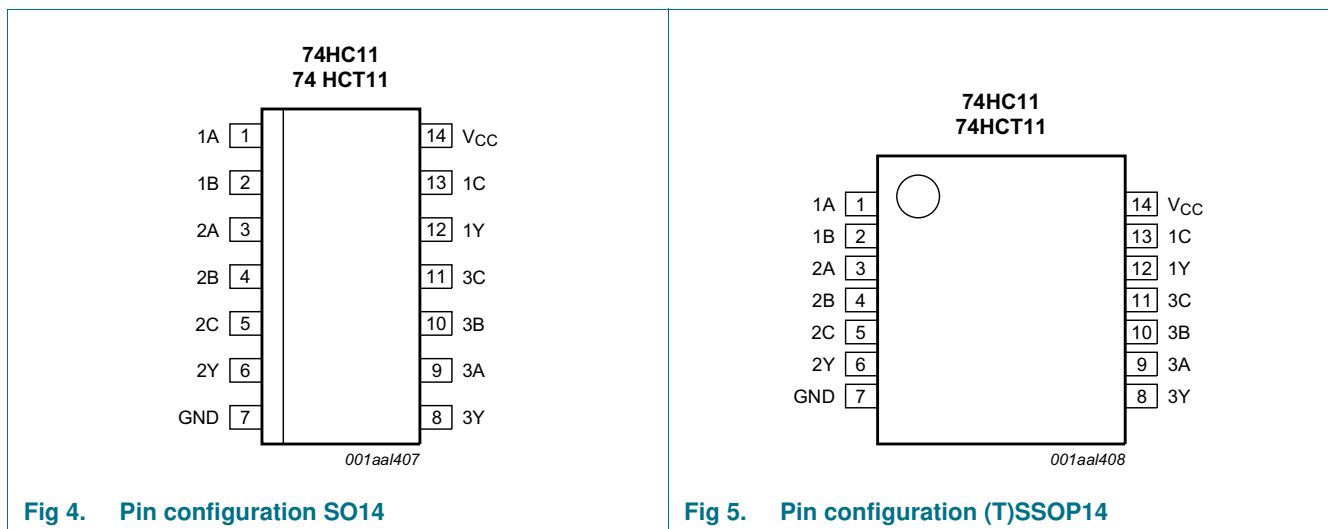


## 4. Functional diagram



## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

Table 2. Pin description

| Symbol          | Pin       | Description    |
|-----------------|-----------|----------------|
| 1A, 2A, 3A      | 1, 3, 9   | data input     |
| 1B, 2B, 3B      | 2, 4, 10  | data input     |
| GND             | 7         | ground (0 V)   |
| 1C, 2C, 3C      | 13, 5, 11 | data input     |
| 1Y, 2Y, 3Y      | 12, 6, 8  | data output    |
| V <sub>CC</sub> | 14        | supply voltage |

## 6. Functional description

Table 3. Function selection<sup>[1]</sup>

| Input |    |    | Output |
|-------|----|----|--------|
| nA    | nB | nC | nY     |
| L     | X  | X  | L      |
| X     | L  | X  | L      |
| X     | X  | L  | L      |
| H     | H  | H  | H      |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol    | Parameter               | Conditions   | Min  | Max      | Unit |
|-----------|-------------------------|--|------|----------|------|
| $V_{CC}$  | supply voltage          |  | -0.5 | +7       | V    |
| $I_{IK}$  | input clamping current  | $V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ | -    | $\pm 20$ | mA   |
| $I_{OK}$  | output clamping current | $V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ | -    | $\pm 20$ | mA   |
| $I_O$     | output current          | $-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$          | -    | $\pm 25$ | mA   |
| $I_{CC}$  | supply current          |  | -    | 50       | mA   |
| $I_{GND}$ | ground current          |  | -50  | -        | mA   |
| $T_{stg}$ | storage temperature     |  | -65  | +150     | °C   |
| $P_{tot}$ | total power dissipation | SO14 and (T)SSOP14 packages                            | -    | 500      | mW   |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.  
For (T)SSOP14 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

| Symbol           | Parameter                           | Conditions              | 74HC11 |      |                 | 74HCT11 |      |                 | Unit |
|------------------|-------------------------------------|-------------------------|--------|------|-----------------|---------|------|-----------------|------|
|                  |                                     |                         | Min    | Typ  | Max             | Min     | Typ  | Max             |      |
| V <sub>CC</sub>  | supply voltage                      |                         | 2.0    | 5.0  | 6.0             | 4.5     | 5.0  | 5.5             | V    |
| V <sub>I</sub>   | input voltage                       |                         | 0      | -    | V <sub>CC</sub> | 0       | -    | V <sub>CC</sub> | V    |
| V <sub>O</sub>   | output voltage                      |                         | 0      | -    | V <sub>CC</sub> | 0       | -    | V <sub>CC</sub> | V    |
| T <sub>amb</sub> | ambient temperature                 |                         | -40    | -    | +125            | -40     | -    | +125            | °C   |
| Δt/ΔV            | input transition rise and fall rate | V <sub>CC</sub> = 2.0 V | -      | -    | 625             | -       | -    | -               | ns/V |
|                  |                                     | V <sub>CC</sub> = 4.5 V | -      | 1.67 | 139             | -       | 1.67 | 139             | ns/V |
|                  |                                     | V <sub>CC</sub> = 6.0 V | -      | -    | 83              | -       | -    | -               | ns/V |

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol          | Parameter                 | Conditions   | 25 °C |      |      | -40 °C to +85 °C |      | -40 °C to +125 °C |      | Unit |
|-----------------|---------------------------|--|-------|------|------|------------------|------|-------------------|------|------|
|                 |                           |  | Min   | Typ  | Max  | Min              | Max  | Min               | Max  |      |
| <b>74HC11</b>   |                           |  |       |      |      |                  |      |                   |      |      |
| V <sub>IH</sub> | HIGH-level input voltage  | V <sub>CC</sub> = 2.0 V  | 1.5   | 1.2  | -    | 1.5              | -    | 1.5               | -    | V    |
|                 |                           | V <sub>CC</sub> = 4.5 V  | 3.15  | 2.4  | -    | 3.15             | -    | 3.15              | -    | V    |
|                 |                           | V <sub>CC</sub> = 6.0 V  | 4.2   | 3.2  | -    | 4.2              | -    | 4.2               | -    | V    |
| V <sub>IL</sub> | LOW-level input voltage   | V <sub>CC</sub> = 2.0 V  | -     | 0.8  | 0.5  | -                | 0.5  | -                 | 0.5  | V    |
|                 |                           | V <sub>CC</sub> = 4.5 V  | -     | 2.1  | 1.35 | -                | 1.35 | -                 | 1.35 | V    |
|                 |                           | V <sub>CC</sub> = 6.0 V  | -     | 2.8  | 1.8  | -                | 1.8  | -                 | 1.8  | V    |
| V <sub>OH</sub> | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                                    |       |      |      |                  |      |                   |      |      |
|                 |                           | I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V                                       | 1.9   | 2.0  | -    | 1.9              | -    | 1.9               | -    | V    |
|                 |                           | I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V                                       | 4.4   | 4.5  | -    | 4.4              | -    | 4.4               | -    | V    |
|                 |                           | I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V                                       | 5.9   | 6.0  | -    | 5.9              | -    | 5.9               | -    | V    |
|                 |                           | I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V                                      | 3.98  | 4.32 | -    | 3.84             | -    | 3.7               | -    | V    |
| V <sub>OL</sub> | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                                    |       |      |      |                  |      |                   |      |      |
|                 |                           | I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V  | -     | 0    | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                 |                           | I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V  | -     | 0    | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                 |                           | I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V  | -     | 0    | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                 |                           | I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V                                       | -     | 0.15 | 0.26 | -                | 0.33 | -                 | 0.4  | V    |
| I <sub>l</sub>  | input leakage current     | V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V                       | -     | -    | ±0.1 | -                | ±1   | -                 | ±1   | μA   |
|                 |                           | V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V | -     | -    | 2.0  | -                | 20   | -                 | 40   | μA   |

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol           | Parameter                 | Conditions  | 25 °C |      |      | -40 °C to +85 °C |     | -40 °C to +125 °C |     | Unit |
|------------------|---------------------------|---|-------|------|------|------------------|-----|-------------------|-----|------|
|                  |                           |   | Min   | Typ  | Max  | Min              | Max | Min               | Max |      |
| C <sub>I</sub>   | input capacitance         |   | -     | 3.5  | -    | -                | -   | -                 | -   | pF   |
| <b>74HCT11</b>   |                           |   |       |      |      |                  |     |                   |     |      |
| V <sub>IH</sub>  | HIGH-level input voltage  | V <sub>CC</sub> = 4.5 V to 5.5 V  | 2.0   | 1.6  | -    | 2.0              | -   | 2.0               | -   | V    |
| V <sub>IL</sub>  | LOW-level input voltage   | V <sub>CC</sub> = 4.5 V to 5.5 V  | -     | 1.2  | 0.8  | -                | 0.8 | -                 | 0.8 | V    |
| V <sub>OH</sub>  | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V   |       |      |      |                  |     |                   |     |      |
|                  |                           | I <sub>O</sub> = -20 µA   | 4.4   | 4.5  | -    | 4.4              | -   | 4.4               | -   | V    |
|                  |                           | I <sub>O</sub> = -4.0 mA  | 3.98  | 4.32 | -    | 3.84             | -   | 3.7               | -   | V    |
| V <sub>OL</sub>  | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V   |       |      |      |                  |     |                   |     |      |
|                  |                           | I <sub>O</sub> = 20 µA; V <sub>CC</sub> = 4.5 V   | -     | 0    | 0.1  | -                | 0.1 | -                 | 0.1 | V    |
| I <sub>I</sub>   | input leakage current     | V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V  | -     | -    | ±0.1 | -                | ±1  | -                 | ±1  | µA   |
| I <sub>CC</sub>  | supply current            | V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V  | -     | -    | 2.0  | -                | 20  | -                 | 40  | µA   |
| ΔI <sub>CC</sub> | additional supply current | per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; I <sub>O</sub> = 0 A; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V | -     | 100  | 360  | -                | 450 | -                 | 490 | µA   |
| C <sub>I</sub>   | input capacitance         |   | -     | 3.5  | -    | -                | -   | -                 | -   | pF   |

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

GND = 0 V; C<sub>L</sub> = 50 pF; for load circuit see [Figure 7](#).

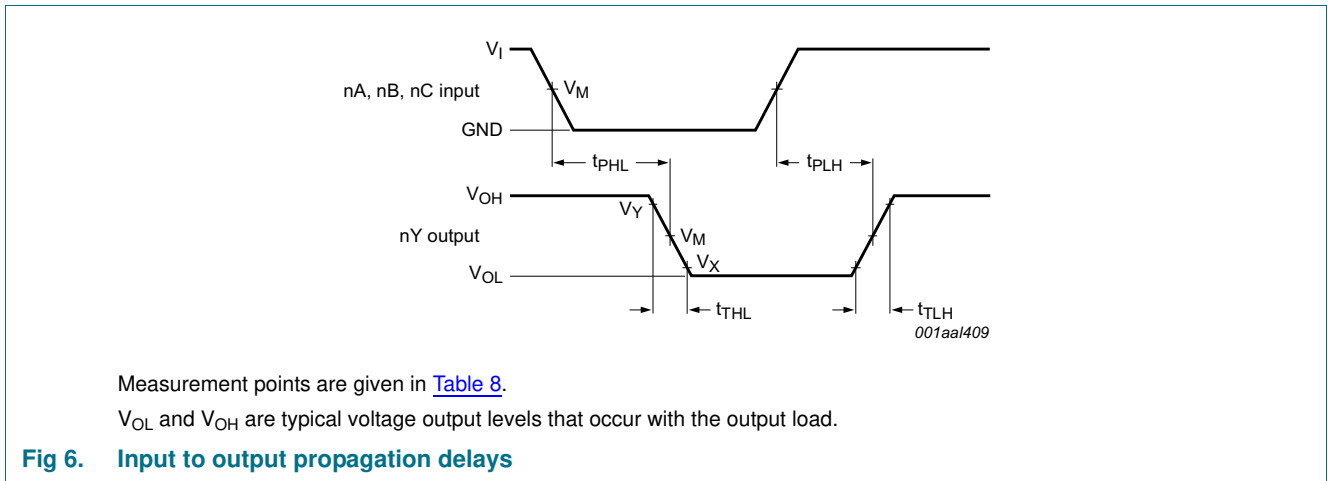
| Symbol          | Parameter                     | Conditions   | 25 °C |     |     | -40 °C to +125 °C |              | Unit |
|-----------------|-------------------------------|--|-------|-----|-----|-------------------|--------------|------|
|                 |                               |  | Min   | Typ | Max | Max (85 °C)       | Max (125 °C) |      |
| <b>74HC11</b>   |                               |  |       |     |     |                   |              |      |
| t <sub>pd</sub> | propagation delay             | nA, nB to nY; see <a href="#">Figure 6</a> <a href="#">[1]</a>           |       |     |     |                   |              |      |
|                 |                               | V <sub>CC</sub> = 2.0 V  | -     | 32  | 100 | 125               | 150          | ns   |
|                 |                               | V <sub>CC</sub> = 4.5 V  | -     | 12  | 20  | 25                | 30           | ns   |
|                 |                               | V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF                          | -     | 9   | -   | -                 | -            | ns   |
|                 |                               | V <sub>CC</sub> = 6.0 V  | -     | 10  | 17  | 21                | 26           | ns   |
| t <sub>t</sub>  | transition time               | see <a href="#">Figure 6</a> <a href="#">[2]</a>                         |       |     |     |                   |              |      |
|                 |                               | V <sub>CC</sub> = 2.0 V  | -     | 19  | 75  | 95                | 110          | ns   |
|                 |                               | V <sub>CC</sub> = 4.5 V  | -     | 7   | 15  | 19                | 22           | ns   |
|                 |                               | V <sub>CC</sub> = 6.0 V  | -     | 6   | 13  | 16                | 19           | ns   |
| C <sub>PD</sub> | power dissipation capacitance | per package; V <sub>I</sub> = GND to V <sub>CC</sub> <a href="#">[3]</a> | -     | 18  | -   | -                 | -            | pF   |

**Table 7. Dynamic characteristics**  
 GND = 0 V;  $C_L = 50$  pF; for load circuit see [Figure 7](#).

| Symbol         | Parameter                     | Conditions   | 25 °C |     |     | -40 °C to +125 °C |              | Unit |
|----------------|-------------------------------|--|-------|-----|-----|-------------------|--------------|------|
|                |                               |  | Min   | Typ | Max | Max (85 °C)       | Max (125 °C) |      |
| <b>74HCT11</b> |                               |  |       |     |     |                   |              |      |
| $t_{pd}$       | propagation delay             | nA, nB to nY; see <a href="#">Figure 6</a> [1]     |       |     |     |                   |              |      |
|                |                               | $V_{CC} = 4.5$ V                                   | -     | 16  | 24  | 30                | 36           | ns   |
|                |                               | $V_{CC} = 5.0$ V; $C_L = 15$ pF                    | -     | 11  | -   | -                 | -            | ns   |
| $t_t$          | transition time               | $V_{CC} = 4.5$ V; see <a href="#">Figure 6</a> [2] | -     | 7   | 15  | 19                | 22           | ns   |
| $C_{PD}$       | power dissipation capacitance | per package; $V_I = GND$ to $V_{CC} - 1.5$ V [3]   | -     | 20  | -   | -                 | -            | pF   |

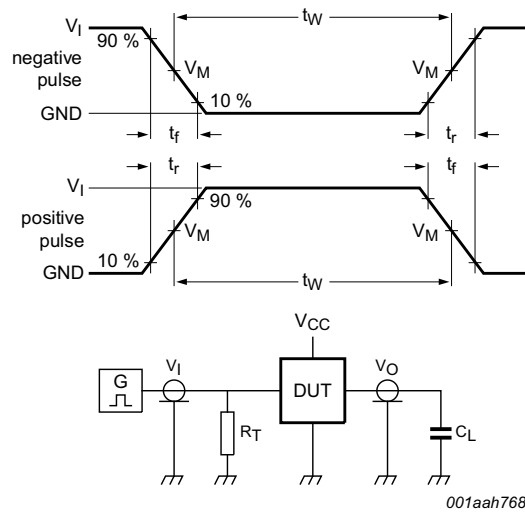
- [1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W):  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 11. Waveforms



**Table 8. Measurement points**

| Type    | Input       | Output      |             |             |
|---------|-------------|-------------|-------------|-------------|
|         | $V_M$       | $V_M$       | $V_X$       | $V_Y$       |
| 74HC11  | $0.5V_{CC}$ | $0.5V_{CC}$ | $0.1V_{CC}$ | $0.9V_{CC}$ |
| 74HCT11 | 1.3 V       | 1.3 V       | $0.1V_{CC}$ | $0.9V_{CC}$ |



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = load capacitance including jig and probe capacitance.

**Fig 7. Test circuit for measuring switching times**

**Table 9. Test data**

| Type    | Input    |            | Load         | Test               |
|---------|----------|------------|--------------|--------------------|
|         | $V_I$    | $t_r, t_f$ | $C_L$        |                    |
| 74HC11  | $V_{CC}$ | 6.0 ns     | 15 pF, 50 pF | $t_{PLH}, t_{PHL}$ |
| 74HCT11 | 3.0 V    | 6.0 ns     | 15 pF, 50 pF | $t_{PLH}, t_{PHL}$ |

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

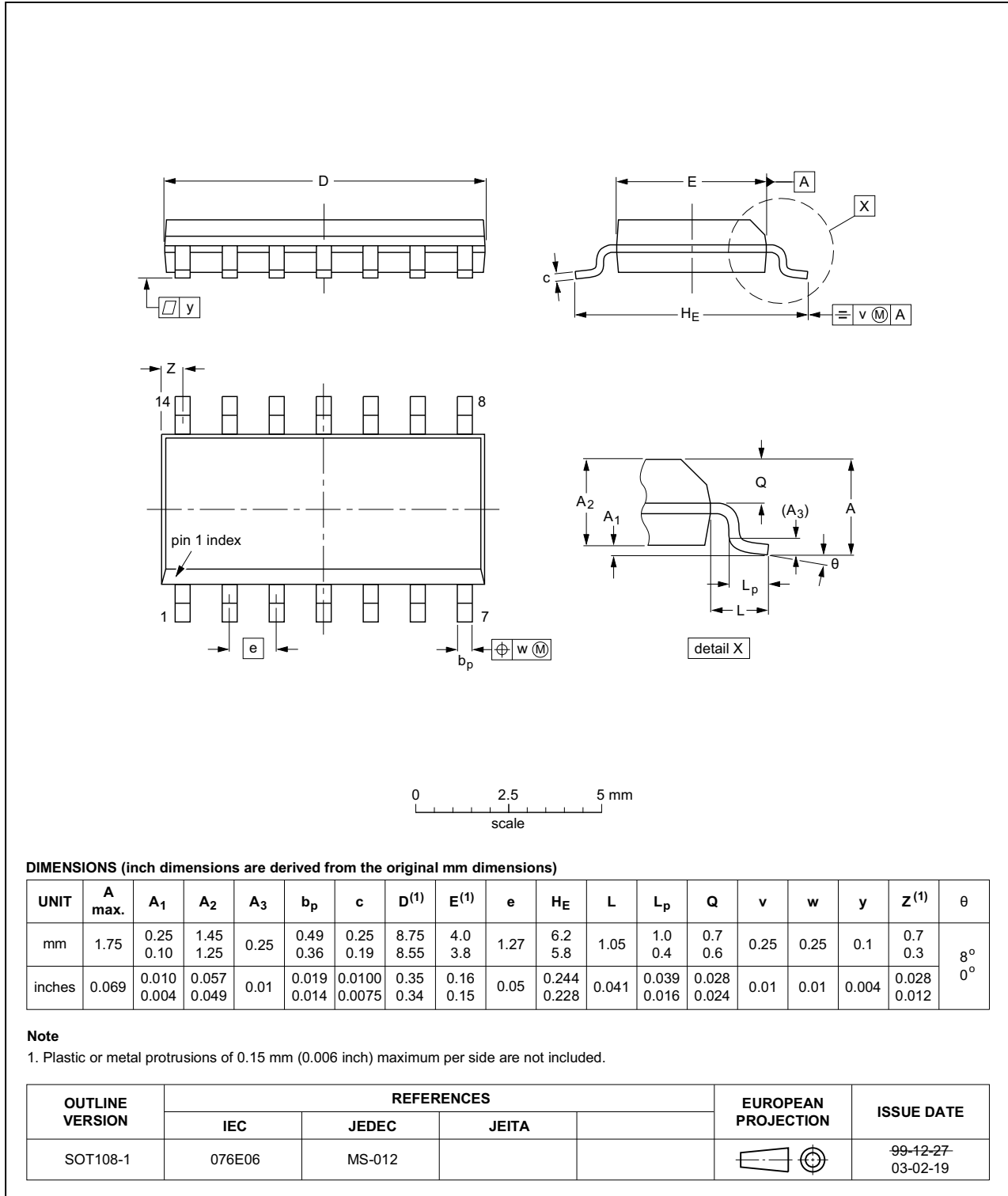


Fig 8. Package outline SOT108-1 (SO14)



SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

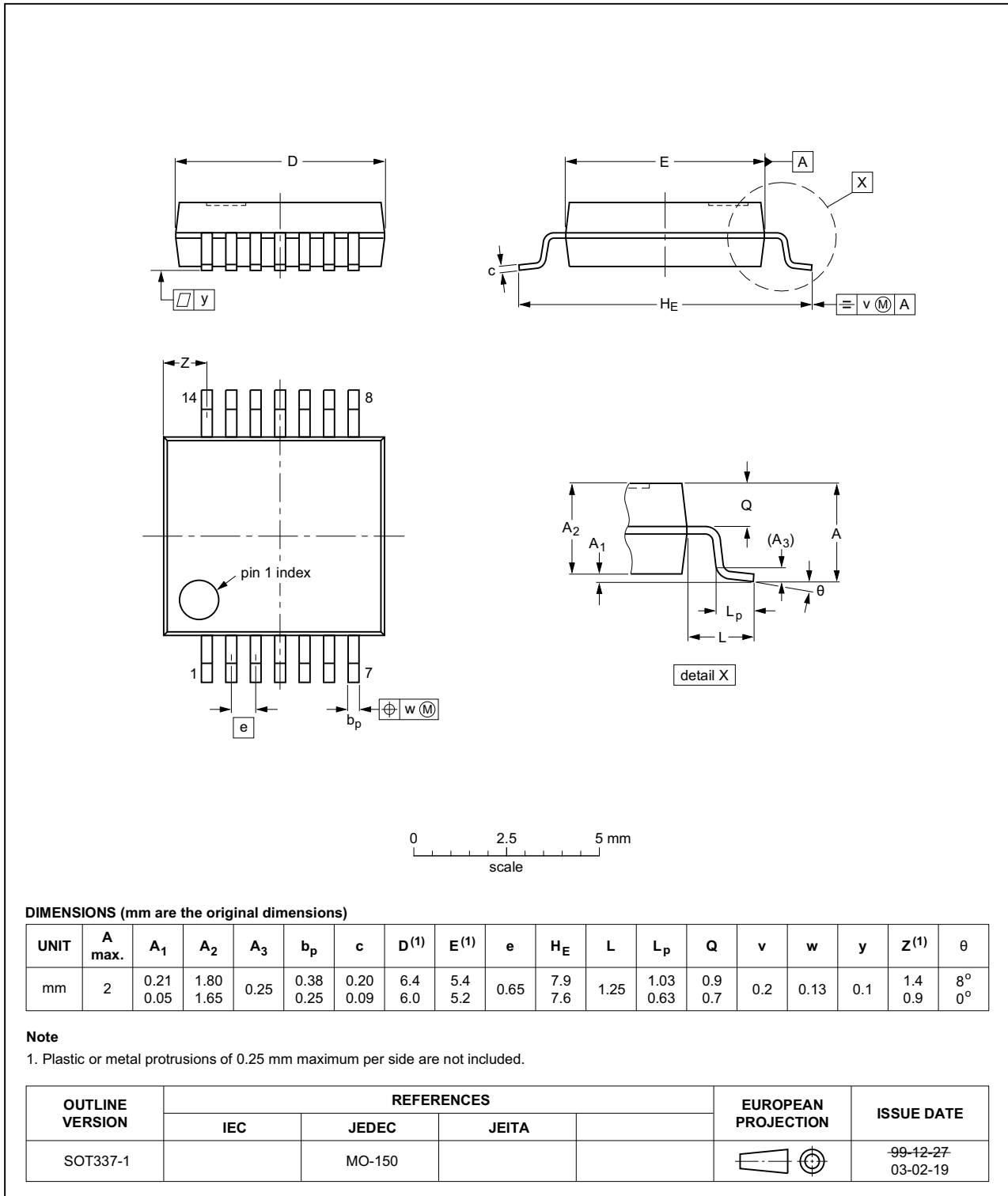


Fig 9. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

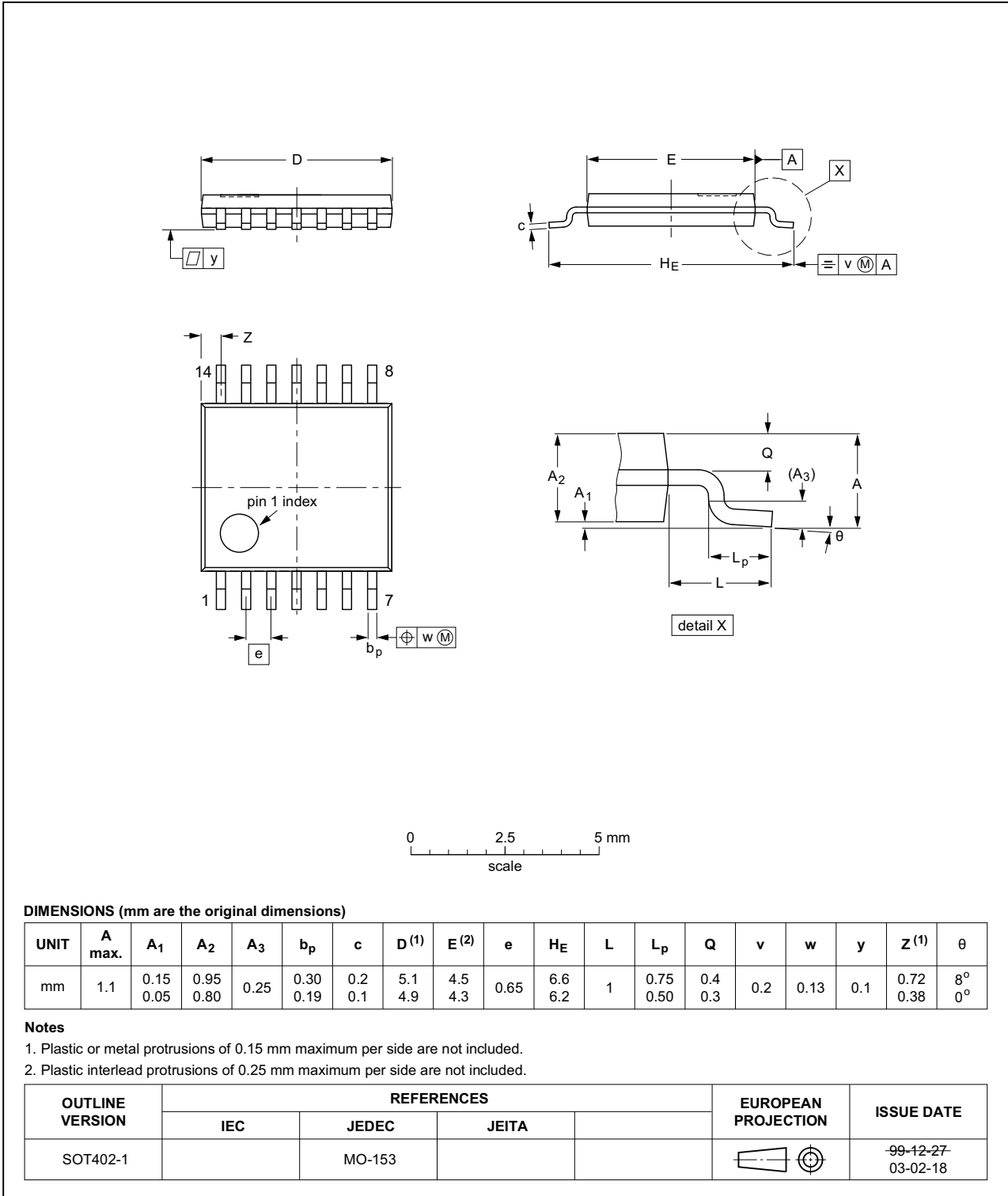


Fig 10. Package outline SOT402-1 (TSSOP14)

## 13. Abbreviations

Table 10. Abbreviations

| Acronym | Description                             |
|---------|---|
| CMOS    | Complementary Metal-Oxide Semiconductor |
| DUT     | Device Under Test                       |
| ESD     | ElectroStatic Discharge                 |
| HBM     | Human Body Model                        |
| MM      | Machine Model                           |
| TTL     | Transistor-Transistor Logic             |

## 14. Revision history

Table 11. Revision history

| Document ID        | Release date   | Data sheet status     | Change notice | Supersedes         |
|--------------------|--|-----------------------|---------------|--------------------|
| 74HC_HCT11 v.6     | 20151119   | Product data sheet    | -             | 74HC_HCT11 v.5     |
| Modifications:     | <ul style="list-style-type: none"> <li>Type numbers 74HC11N and 74HCT11N (SOT27-1) removed.</li> </ul> |                       |               |                    |
| 74HC_HCT11 v.5     | 20111216   | Product data sheet    | -             | 74HC_HCT11 v.4     |
| Modifications:     | <ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>                                 |                       |               |                    |
| 74HC_HCT11 v.4     | 20100325   | Product data sheet    | -             | 74HC_HCT11 v.3     |
| 74HC_HCT11 v.3     | 20100209   | Product data sheet    | -             | 74HC_HCT11_CNV v.2 |
| 74HC_HCT11_CNV v.2 | 19970827   | Product specification | -             | -                  |

## 15. Legal information

### 15.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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